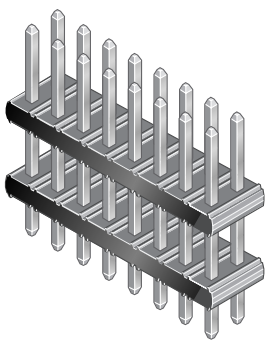
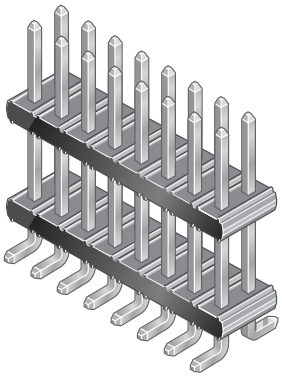
Minitek™ Unshrouded Stacking Headers 2,00 mm

FCI basics

- **CUSTOMISABLE:** Wide variety of stack heights in 0.13 mm increments
- Custom sizes to meet your specific design requirements
- High temperature plastic





24 HOUR SAMPLES

Technical Data

Physical

Housing: High-temperature, black thermoplastic

Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: Gold over 1.27 µm nickel

Electrical Performance

Current rating: 2 A continuous

Insulation resistance: 1000 MΩ min.

Contact resistance: 25 mΩ max.

Dielectric withstanding voltage: 650 V

Voltage rating: 200 V

Mechanical Performance

Mating cycles (durability): 100

Operating Temperature

-55°C to +125°C

Packaging

Standard: TMT in bags
SMT in Tape-and-reel

Optional: Tubes (see drawing)

Reference Information

File no. E66906

File no. LR46923

Product drawing: 59112, 59132, or 59202

Product specification: DPS-12-011

Specifications subject to change without notice.

Mating Data

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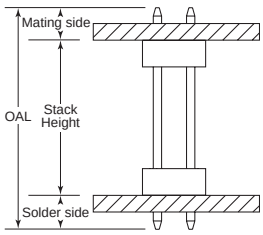
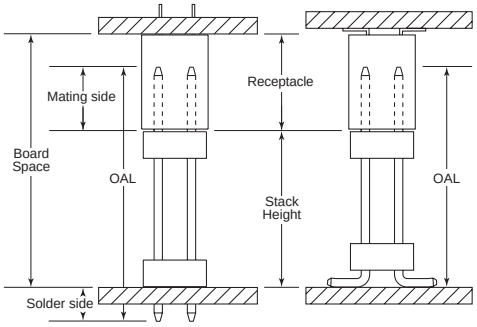
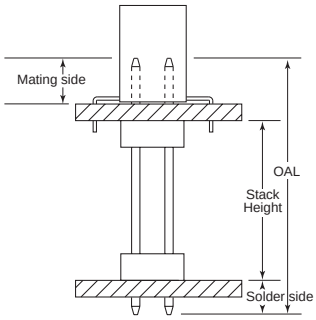
Processing Information

Compatible with wave, vapor-phase, and IR reflow soldering processes

Typical Applications







Part Number

5	9	Lead	Solder Side Option	2	–	Plating	Pin Style	–	Positions Per Row	–	Stack Height

1 = Through Mount (TMT)
2 = Surface Mount (SMT)

1 = 2.50
3 = 3.00
0 = SMT

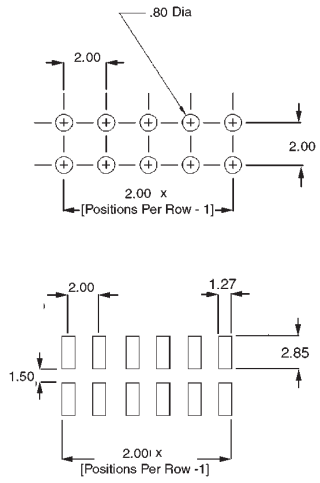
G = 0,76 µm Gold on mating area, 2-6 µm Tin-Lead on solder side
F = Gold flash

02 to 25 (TMT)
02 to 25 (SMT)

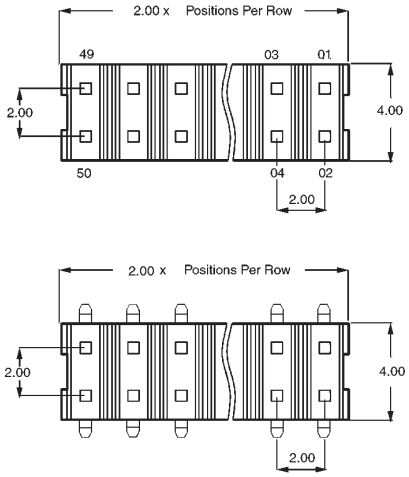
XX.X = mm
Specify mm
[i.e., 037 = 03.7 mm]
in 0.1 mm increments

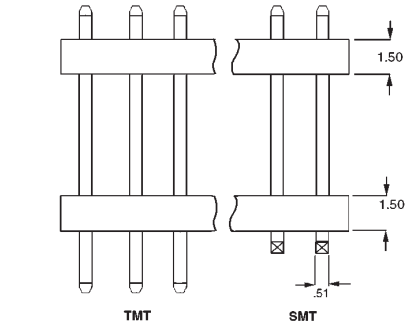
PACKING:
– = Bags (TMT)
A = Tape-and-reel (SMT)

Pin Style	OAL (TMT) mm	Height (SMT) mm
22	8.20	6.53
24	9.55	7.87
26	10.19	8.51
28	11.79	10.11
30	13.54	11.86
32	14.10	12.42
34	15.60	13.92
36	17.09	15.42
38	19.08	17.40
40	21.08	19.41



Recommended PCB Layout





Step-by-Step Design

1. Determine desired board spacing
2. Select receptacle and calculate stack height
   Stack Height = Board Spacing – Receptacle Height
3. Find the insertion depth from the chart below. Calculate max./min. OAL
   OAL = Stack Height + Tail + Insertion Depth
4. Select the Pin Style with OAL between max. and min. values

	RECEPTACLES	
	TMT	SMT
Height (mm)	4.50	2.30
Insertion Depth (max.)	4.30	2.20
Insertion Depth (min.)	3.03	1.43

Example:

1. Application requires a board spacing of 14.1
2. Select the appropriate receptacle, in this case 3.0 height (SMT)
   The Header Stack Height is 14.1 – 3.0 = 11.1
3. For 1,6 mm board application (TMT), the 2.5 Solder side is selected
   OAL (max.) = 14.1 + 2.5 + 3.4 = 20.0
   OAL (min.) = 14.1 + 2.5 + 1.28 = 17.88
4. Select Pin Style 38 with OAL = 19.07
5. Part Number is 59112-G38-10-141

Dimensions in mm